



TOLERANCE: ±0.05, THICKNESS : 1.2 mm
RECOMMENDED PCB LAYOUT

5	STDA_SSRX-	9	STDA_SSTX+
4	GND	8	STDA_SSTX-
3	D+	7	GND_DRAIN
2	D-	6	STDA_SSRX+
1	VBUS		
PIN#	SLGNAL NAME	PIN#	SLGNAL NAME

NOTE:

- MATERIAL:
 - INSULATOR: LCP+30%GF, UL94 V-0.
 - CONTACT 1~4PIN: 铜合金
 - CONTACT 5~9PIN: 铜合金
 - SHELL: SUS304 3/4H
- PLATING:
 - CONTACT:
 - CONTACT AREA: GOLD PLATING.
 - SOLDER AREA: 100u" Min MATTE TIN PLATING.
 - UNDER PLATE: 50u" Min NICKEL PLATING.
 - SHELL: 50u" Min. NICKEL PLATED OVERALL
- CHARACTERISTICS:
 - ELECTRICAL CHARACTERISTICS:
 - CONTACT RESISTANCE: 30mΩ MAXIMUM
 - CONTACT CURRENT RATING: 3A
 - DIELECTRIC WITHSTANDING VOLTAGE: 500 V
 - M.S.
 - INSULATION RESISTANCE: 1000 MEGOHMS
 - MIN OPERATING TEMPERATURE: -25~C ~ +85°C
 - MECHANICAL:
 - Before lifespan: insertion force 8-25N; pull-out force 10-25N.
 - After lifespan: 6N Min.
- PART MUST COMPLY ROHS SPECIFICATION
- SOLDER RESISTANCE TEMPERATURE: 260 ± 5°C FOR 3 MINUTES.

3	SHELL	SUS304-3/4H	50u" Min. NICKEL PLATED OVERALL
2	CONTACT	铜合金	Overall nickel plating 50u" ~ 100u", contact area gold plating 1U", welding leg tin plating 100u"
1	HSG	LCP+30%GF	BLUE UL94V-0
NO.	PART NAME	MATERIAL	DESCRIPTION



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2' X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: USB 3.0 AF 沉板DIP 板上3.3 无卷边
	CHECKED BY : 马跃	DATE : 2014-02-23	PART NO. : HVC181-USBA09-330
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY : 邱敏	DATE : 2014-02-23	DRAW NO. : HVC-2604281457
			SHEET NO. : 1 OF 1